



Tab settings

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To the Honorable Commissioner of Patents at _____,ed original documents or copy thereof.

1. Name of conveying party(ies):

David J. Corisis

2/19/99

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Internal Address: _____

Street Address: 8000 South Federal Way

City: Boise State: ID ZIP: 83706-9632

Additional name(s) & address(es) attached? Yes No

jc551 U.S. PTO
09/253227
02/19/99

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: February 1, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 02/01/99

A. Patent Application No.(s)

B. Patent No.(s)

Filed Herewith

Additional numbers attached? Yes No

09/253227

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: James D. Shaurette

Internal Address: Wells, St. John, Roberts, Gregory & Matkin P.S.

Street Address: 601 West First Avenue, Suite 1300

City: Spokane State: WA ZIP: 99201-3828

6. Total number of applications and patents involved:

7. Total fee (37 CFR 3.41) \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

23-0925

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

James D. Shaurette

Name of Person Signing

[Signature]

Signature

February 19, 1999

Date

Total number of pages including cover sheet, attachments, and document:

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT:

Inventor:

David J. Corisis
961 West Loon Street
Meridian, Idaho 83642

Assignee:

Micron Technology, Inc.
Corporation of the State of Delaware
8000 South Federal Way
Boise, Idaho 83706-9632

BACKGROUND OF THIS ASSIGNMENT:

INVENTOR has conceived certain new and useful inventions disclosed in a United States patent application titled Integrated Circuit Packages, Ball-Grid Array Integrated Circuit Packages and Methods of packaging an Integrated Circuit.

MICRON TECHNOLOGY, INC. desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

THE PARTIES AGREE AS FOLLOWS:

In consideration of the sum of \$1.00 and other good and valuable consideration, the receipt of which is hereby acknowledged, INVENTOR has sold, assigned and transferred to MICRON TECHNOLOGY, INC. the full and exclusive right to said inventions in the United States and in all foreign countries.

1 INVENTOR does hereby sell, assign and transfer to MICRON
2 TECHNOLOGY, INC. the entire right, title and interest in the
3 above-identified application executed concurrently with this assignment
4 and to any reissues, divisions or continuations thereof, and hereby
5 authorizes the Commissioner of Patents and Trademarks to issue such
6 Letters Patent to MICRON TECHNOLOGY, INC. for the sole use of
7 MICRON TECHNOLOGY, INC., its successors or assigns.

8 INVENTOR further agrees to execute, at the request and expense
9 of MICRON TECHNOLOGY, INC. such other formal documents as may
10 be required to fully convey the interest transferred herein and will
11 similarly execute any applications papers required for the filing of any
12 division, continuation or reissue of the patent application or resulting
13 Letters Patent; and will generally do everything necessary or desirable
14 to obtain and enforce proper protection for the invention assigned
15 hereby.

16 INVENTOR further assigns to MICRON TECHNOLOGY, INC. the
17 whole right, title and interest in the invention disclosed in the
18 application throughout all countries foreign to the United States.
19 MICRON TECHNOLOGY, INC. is hereby authorized to apply for
20 patents relating to the inventions in its own name in countries where
21 such procedure is proper; to claim the benefit of the International
22 Convention; to file and prosecute International Applications relating to
23 the inventions under the Patent Cooperation Treaty; and to file and
24 prosecute applications relating to the inventions under the European

1 Patent Convention. INVENTOR agrees to execute applications relating
2 to the inventions in those countries and under those conventions where
3 it is necessary that the same be executed by the inventor, and to
4 execute assignments of such applications and the resulting Letters Patent
5 to MICRON TECHNOLOGY, INC. as well as all other necessary papers
6 in relation to such applications and Letters Patent.

7 Signed at Boise on 2-1,

8 1999.

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10 David J. Corisis
11 David J. Corisis
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